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Cogiscan

Hands-On, Lead-Free 2-Day Technology Workshop

March 16 & 17, 2005, 8am - 5pm
Engent, 3140 Northwoods Parkway, Norcross GA 30071

Hands-On Lead-Free Training

This comprehensive 2-day, hands-on training program will provide participants with a broader knowledge of lead-free material interactions and a greater understanding of the process, including advantages and limitations. A sample lead-free board manufactured over the two-day course will be produced and taken away by each attendee.

Panel of Industry Experts Include:

Dr. Neil Poole – Henkel Technologies

- Material interactions
- Surface mount adhesives
- Underfills
- Conformal coatings
- Alloy reliability

Dr. Daniel Baldwin – Engent

- Process engineering methods
- DOE
- Analytical tools

Francois Monette – Cogiscan Inc.

- Material logistics and identification
- Component compatibility
- Impact on MSD

Marybeth Allen – KIC

- Management of the thermal processes as they relate to the conversion to lead-free manufacturing

Keith Howell – Speedline Technologies

- Wave and reflow processes

Hands-On Production Floor Training:

- Screen printing surface mount adhesives and solder paste, and placement
- Reflow profiling
- Inspection/analytical
- Rework
- Wave

Who Should Attend?

- Engineers & engineering management

“The unique format of this course definitely made it worth the trip! I was able to learn from leading market experts and had the opportunity to build a printed circuit board assembly using the latest lead-free materials, components and state-of-the-art equipment – all factors that I know will ensure the success of our company as we make the lead-free transition.”

Randy Cherry, lead process engineer at Tellabs

Space is limited, so register early \$495 per person. Reservations must be made by March 9, 2005
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